

# semiconductor packaging news

## EV Group Expands Collaboration with ITRI on Heterogeneous Integration Process Development – September 6, 2022

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We search for industry news, so you don't need to.

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September 6, 2022

### [New U.S. Rule Could 'Impair' China's AI Progress](#)

The U.S. government's fresh restrictions on sales of Nvidia GPUs are expected to slow China's AI progress, which one analyst says leads the world. The U.S. has placed controls on sales of chips to China and Russia over concerns that the processors may have military uses. The measure is the latest salvo in a tech war between the U.S. and China that began under the administration of former ...

EE Times



### [Do you need wafer-wands with flexible hoses?](#)

Our push button wafer wands turn off the air-flow when the wand is returned to the mating wand holder. Conserves factory air supply.

Virtual Industries, Inc.



### [Need surface or material modification?](#)

YES systems offer proven & reliable technology for thermal processing, wet processing, plasma etching & monolayer coating. Configurations from tabletop lab/R&D systems to HVM production.

Yield Engineering Systems



### [Global Smartphone Shipments Expected to Decline 6.5% in 2022, Amidst Global Inflation and Softer Demand, According to IDC](#)

According to the latest International Data Corporation (IDC) Worldwide Quarterly Mobile Phone Tracker forecast, shipments of smartphones will decline 6.5% to 1.27 billion ...

IDC

### [Effects of Long-Term Storage on Mechanical and Electrical Integrity](#)

This white paper examines the effects on mechanical integrity and electrical performance of semiconductor components stored for up to 17 years to enable long lifecycle ...

Technical Paper

### [\\$15 Billion Micron Fab to Improve U.S. DRAM Supply](#)

Micron Technology, the world's third-largest memory chip manufacturer, said that it plans to build the first memory fab in 20 years in the United States. Micron is set to invest ...

EE Times

## Technical Papers

- [Effects of Long-Term Storage on Mechanical and Electrical Integrity](#)
- [The Great Debate: Ball Bonding vs Wedge Bonding](#)
- [Chip-Last HDFO Interposer-PoP](#)
- [Air Gap, Buried Layer and Micro-Channel Measurement](#)
- [Essential Practices for Gold Mitigation of Electronic Components](#)
- [The Journey to Full-Scale Semiconductor Packaging Manufacturing](#)
- [Dispositioning Hermetic Microelectronic Components With High Internal Moisture](#)

### [Buy Ceramic Dispensing Needles Online](#)

Ceramic needles with Luer Lok for conductive epoxies and encapsulation. The ceramic molding process allows for smaller more precise inner diameters with a glass like finish. Buy Online.



DL Technology

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### Test Your Knowledge

The transistor was invented by engineers at Bell Labs. What year was it invented?

See answer below.

### [High Precision Automated Die Sorting](#)

Sort all device types regardless of substrate type, thickness, die size or form factor. The AP+ offers highly flexible configurations for the most challenging sorting applications.



Royce Instruments

## Press Releases

### [EV Group Expands Collaboration with ITRI on Heterogeneous Integration Process Development](#)

EV Group (EVG) announced that it has expanded its collaboration with the Industrial Technology Research Institute (ITRI), one of the world's leading applied technology ...

EV Group

### [Indium Corporation Experts to Present at IMAPS 2022](#)

Three Indium Corporation experts will share their industry knowledge and expertise during four presentations at the 55th International Symposium on Microelectronics (IMAPS) ...

Indium Corporation

### [Supply Tightening Expected for Specialty Electronic Gases](#)

TECHCET reports that the supply of Specialty Gases, nitrogen trifluoride (NF3) and tungsten hexafluoride (WF6) for electronics could tighten

### Achieving Success in Automotive Leadframe Packages

The auto market consumes leadframe packages. The industry depends on OSAT suppliers to provide wirebond leadframe packaging support. Read more.  
**Amkor Technology, Inc.**



### Power of Experience: Proven SiPaste®

Boost SPI yields with SiPaste® C201HF. Formulated for fine feature printing, it combines cleanability in water-based solutions with excellent transfer efficiency.  
**Indium Corporation**



### Samsung's foundry plant construction to strengthen Korea-US chip ties

Samsung's U.S. foundry plant construction is expected to strengthen Korea-U.S. semiconductor ties, with the company conducting large-scale recruitment of local workers ...

**The Korea Times**

### Chip firms to face earnings challenges in 2025

The local semiconductor industry is expected to face earnings challenges in 2025 as profit growth is likely to peak this year, the Taipei-based China Credit Information Service ...

**Taipei Times**

### PC shipments expected to drop this year

Global PC shipments are forecast to drop significantly this year from last year, with further contraction expected next year due to persistent headwinds, research firm IDC ...

**Taipei Times**

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### Economics minister talks semiconductors, EVs in Japan

Minister of Economic Affairs Wang Mei-hua returned from Japan, where she held talks on bilateral cooperation, including on semiconductors and electric vehicles (EVs), the ...

**Taipei Times**

### Metamaterials Could Solve One of 6G's Big Problems

For all the tumultuous revolution in wireless technology over the past several decades, there have been a couple of constants. One is the overcrowding of radio bands ...

**IEEE Spectrum**

### Broadcom upbeat as it evades chip slump

Chipmaker Broadcom Inc gave a robust sales forecast for this quarter, allaying fears that spending on Internet infrastructure is slowing. Revenue in the fiscal ...

**Taipei Times**

### Sintering Bonding Process

During the sintering process, the chip is bonded very well to the substrate by means of silver paste. The silver particles are connected to one another by diffusion processes.  
**Tresky Automation**



### Die Attach for Road-Ready Reliability

Seems difficult, but this long-desired balance has been achieved. Non-electrically conductive + high thermal + good dispense performance = Auto 0-standard reliability. Learn more.  
**Henkel Corporation**



amongst high projected demand ...  
**TECHCET**

### Automate Your Hi-Mix Die Attach

MAT 6200 Crossover, low cost, entry level auto Die-Attach ideal for low volume Prototypes, NPI, CMS environments. Easy GUI Set-up, Rapid turnover, Multi-Process support.  
**MicroAssembly Technologies**



### Quote of the Day

"Never make a defense or apology before you be accused."

**King Charles I**

### Custom Substrate Design & Fabrication

Have a unique package? We design custom RF packages for 5G and complex BGA for wirebonded or flip chip devices, and more. Contact us to learn more.  
**QP Technologies**



### Diamond's thermal management properties enable higher performance

A collaboration between Univ. of Bristol and Element Six is accelerating diamond's path towards unlocking highly efficient thermal management solutions.  
**Element Six**



### What Year Was It?

#### First Tank Produced

A prototype tank nicknamed Little Willie rolls off the assembly line in England. It weighed 14 tons, got stuck in trenches and crawled over rough terrain at only two miles per hour.



**The day was Sep 6. What year was it?**

### Thermal Interface

#### Adhesives/Greases/Gels/Pads

Electrical and/or thermal die, component and substrate attaches, patented compressible phase-change pads, and non-drying greases proven for over 40 yrs.  
**AI Technology, Inc.**



### Need Tin Mitigation Services?

Watch a video showing precision robotic component tinning. Fully programmable robotic hot solder dip machines control dip depth, dwell times & temps to meet GEIA-0006 standards.  
**Circuit Technology Center**





### [Improving Safety And Security For Tomorrow's Autonomous Vehicles](#)

With the evolution of autonomous vehicles, today's cars are becoming both more connected and complex. Consumers and suppliers worldwide are demanding much more ...  
**Semiconductor Engineering**

### [Week In Review: Manufacturing, Test](#)

At an event in Arizona, U.S. Commerce Secretary Gina Raimondo urged states to compete for funding made available for producing semiconductors by the U.S. federal ...  
**Semiconductor Engineering**

### [Why Arm's lawsuit against Qualcomm is a big deal](#)

Arm is suing Qualcomm, putting two of the most valuable semiconductor firms into direct conflict, and raising questions about the future of the partnership between ...  
**CNBC**



### Cartoon of the Day



"If we provide great customer service, people will pester us with a bunch of stupid questions. Do we really want that?"

Copyright © Randy Glasbergen

### Optimizing cycle times with Openair-Plasma

Plasma surface treatment has uses in semiconductor manufacturing, such as wire bonding, die bonding, thermal compress bonding, and pre-molding.  
**Plasmatrete GmbH**



### Calendar

- [Sep 6, 2022: MEMS & Imaging Sensors Summit](#)
- [Sep 12, 2022: Overview of semiconductor manufacturing](#)
- [Sep 14, 2022: SEMICON Taiwan](#)
- [Sep 14, 2022: Intro to Semiconductor Design & Fabrication Webinar for American Attendees](#)

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**Tresky Automation**

#### Die Attach for Road-Ready Reliability

Seems difficult, but this long-desired balance has been achieved. Non-electrically conductive + high thermal + good dispense performance = Auto 0-standard reliability. Learn more.



**Henkel Corporation**

### Test Your Knowledge Answer

The transistor was invented by engineers at Bell Labs. What year was it invented?

Answer: 1947 by John Bardeen, William Shockley and Walter Brattain at Bell Labs and in 1956, they were awarded the Nobel Prize in Physics "for their researches on semiconductors and their discovery of the transistor effect".

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